

AMENDMENTS TO THE CLAIMS

1-13. (Cancelled)

14. (New) A method for fabricating a substrate, said substrate including a plurality of chip package substrates, comprising the steps of:

providing one combined PCB, including a flexible PCB and a multi-layer rigid PCB fixed on a top surface of said flexible PCB;

forming at least one pair of grooves on an upper surface of said multi-layer rigid PCB;

milling a portion of said multi-layer rigid PCB between said at least one pair of grooves for exposing a corresponding portion of said flexible PCB to define an exposed area;

drilling through said combined PCB along two opposite sides of said at least one pair of grooves and said corresponding exposed area of said flexible PCB; and

forming breakable parts at a center of said corresponding portion of said flexible PCB and two opposite outside edges of said at least one pair of grooves.

15. (New) The method for fabricating a substrate according to claim 14, wherein said at least one pair of grooves are formed by milling.

16. (New) The method for fabricating a substrate according to claim 14, further comprising the step of breaking said breakable parts to separate said chip package substrates.